



Advance Product Change Notification

201602003A

Issue Date: 18-Feb-2016

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



QUALITY

Change Category

- | | | | |
|---|---|---|--|
| <input checked="" type="checkbox"/> Wafer Fab process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Design |
| <input checked="" type="checkbox"/> Wafer Fab materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specification |
| <input type="checkbox"/> Wafer Fab location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Test Location | <input type="checkbox"/> Packing/Shipping/Labeling |

Release of 8 inch wafer diameter for low VCEsat (BISS) transistors

Details of this Planned Change

Release of production using 8 inch wafer diameter for products in SOT23 and SOT89 (SC-62) package. In addition the metal thickness of the top metallisation will be adapted for BISS transistors with 2.1µm top metal.

Old products: Production using 6 inch wafer diameter, top side metallisation thickness 2.1µm (for affected BISS transistors)

Changed products: Production using 6 and 8 inch wafer diameter, top side metallisation thickness 2.2µm (for affected BISS transistors with 8 inch wafers)

Production on 8 inch wafer diameter implies the use of the respective 8 inch wafer process technology.

Why do we Plan this Change

To increase flexibility and volume ramp-up.

Identification of Affected Products

The 8 inch products can be identified by a marker on the die surface.

Product Availability

Sample Information

Sample planning follows with the final PCN

Production

Planned first shipment 24-Jul-2016

Impact

No impact to the products' functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Supply using 6 inch wafer will be continued.

Timing and Logistics

The Self Qualification Report will be ready on 11-Apr-2016.

The Final PCN is planned to be issued on: 11-Apr-2016.

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 19-Mar-2016.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name GA Customer Support

e-mail address DiscrQA.Helpdesk.GA-Products@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP's Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

| [Privacy Policy](#) | [Terms of Use](#)

NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2010 NXP Semiconductors. All rights reserved.